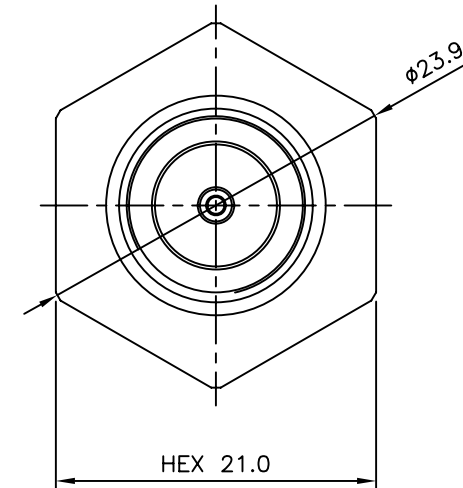
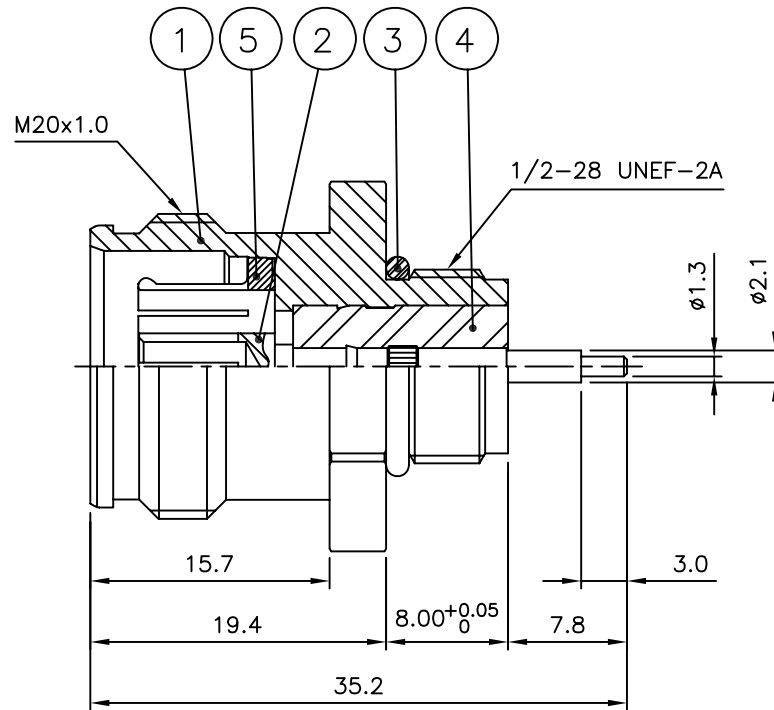


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM		2016. 05. 25.
↑	[설번처리No.201704-0011] JACK 표준화 적용 CODE로 변경	I.C.KIM		2017. 04. 27.



5	JACK	1	MBsBD C3604BD-F	Silver Plate (3 μ m)	DJA00228-5/6 DJA00228-5/2
4	INSULATOR	1	TEFLON		DIN02769-N/1
3	GASKET	1	SILICONE RUB		DGK00121-N/1
2	CONTACT	1	BeCu C17300	Silver Plate (5 μ m)	DCT03693-5/3
1	BODY	1	MBsBD C3604BD-F	SUCO Plate (3 μ m)	DBD04165-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2017. 04. 27.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY		
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE 4.3-10 DIN50 SOLDER END JB (F/F)
		DRAWN BY	I.C.KIM	
FINISH		SCALE	2/1	A4 DWG NO. CN03601-7/1 REVISION 1 SHEET 1 of 1
		UNIT	mm	

KJ